



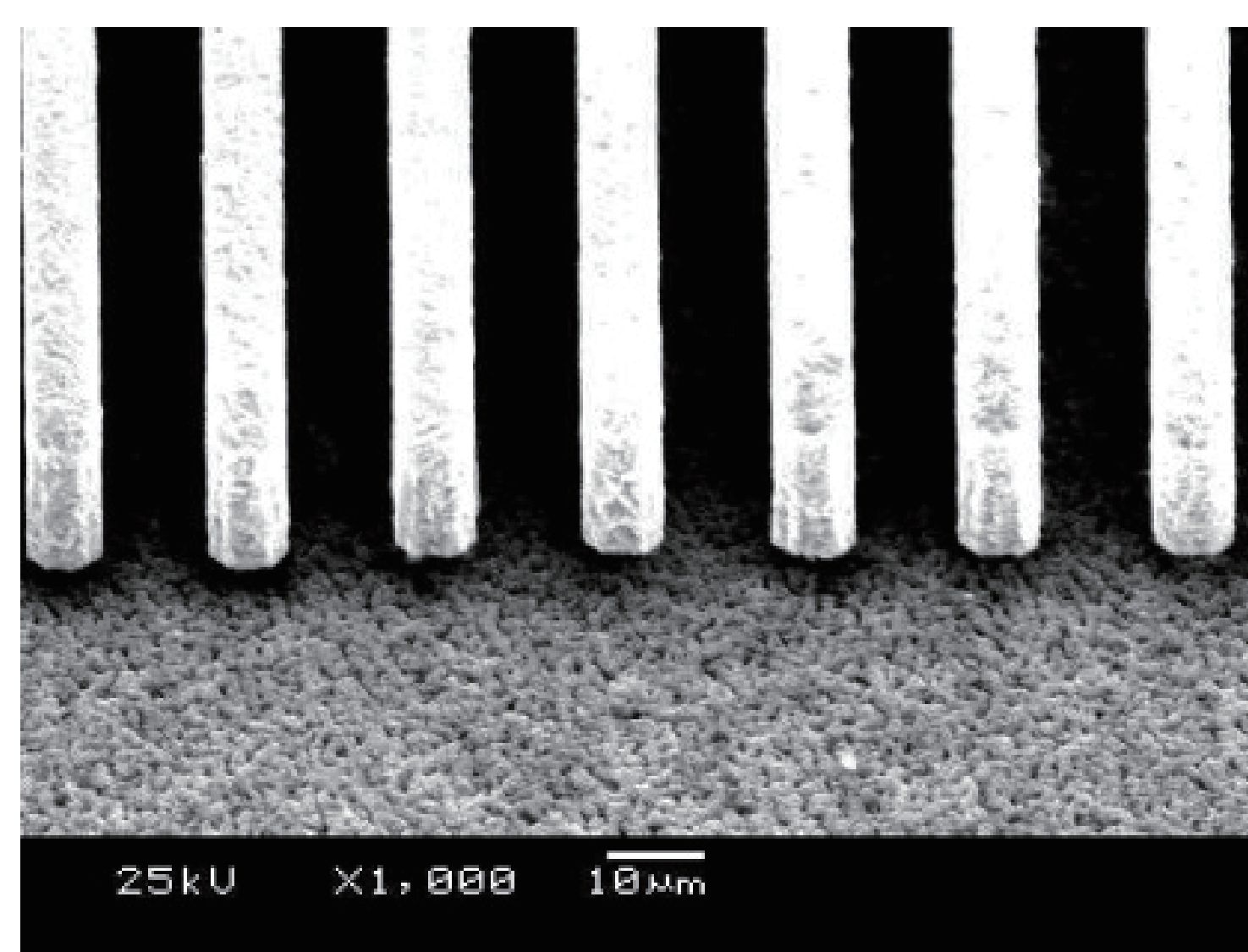
熱硬化型層間絶縁材料 Zaristo Series

Thermal curable Build up Material for SAP

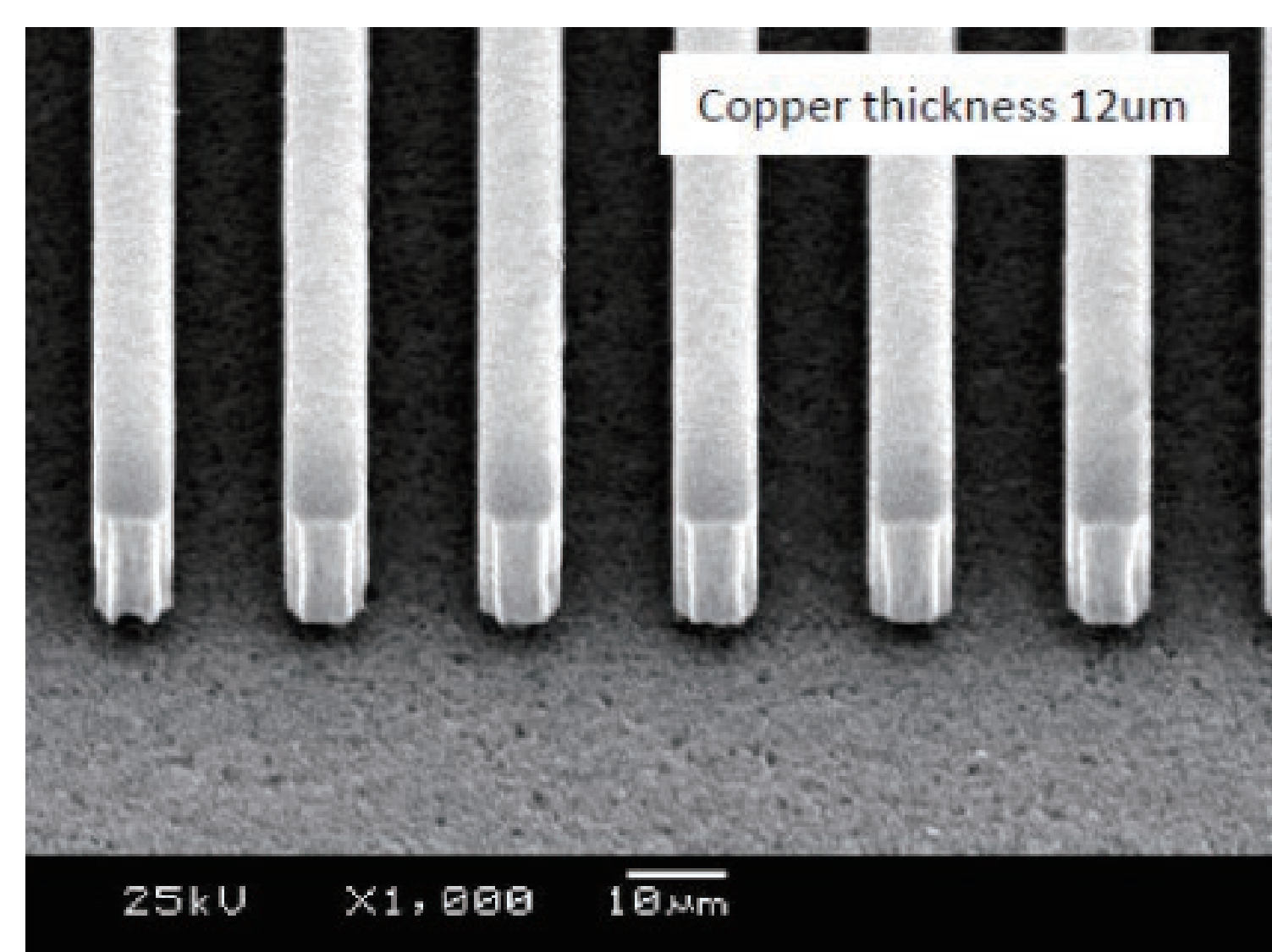
Zaristo125 / Zaristo 517 X (Thermal curable Dry film for SAP)

特徴 Features

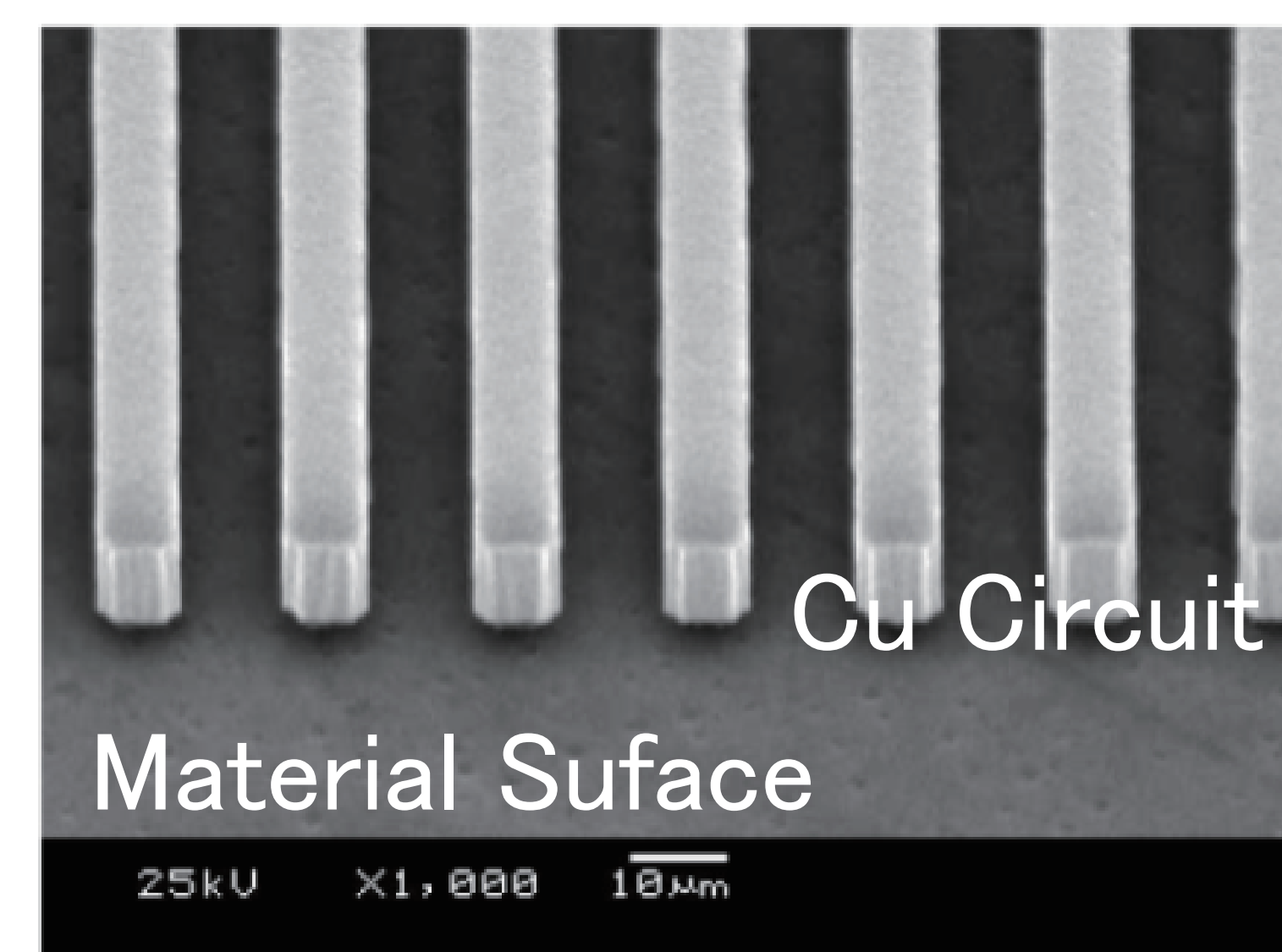
- SAP対応 Suitable for Conventional SAP
- 高BHAST耐性 Excellent LtL & L/S BHAST stability



Conventional BUM DF



Zaristo 125



Zaristo 517X

Fig. FLS(L/S=10/10um) on Zaristo

Zaristo 907 (Thermal curable Dry film for MIS, ETS)

特徴 Features

- 超低反り Ultra Low Warpage after cure
- 低熱膨張&低弾性DF Low CTE & Low Modulus Dry film

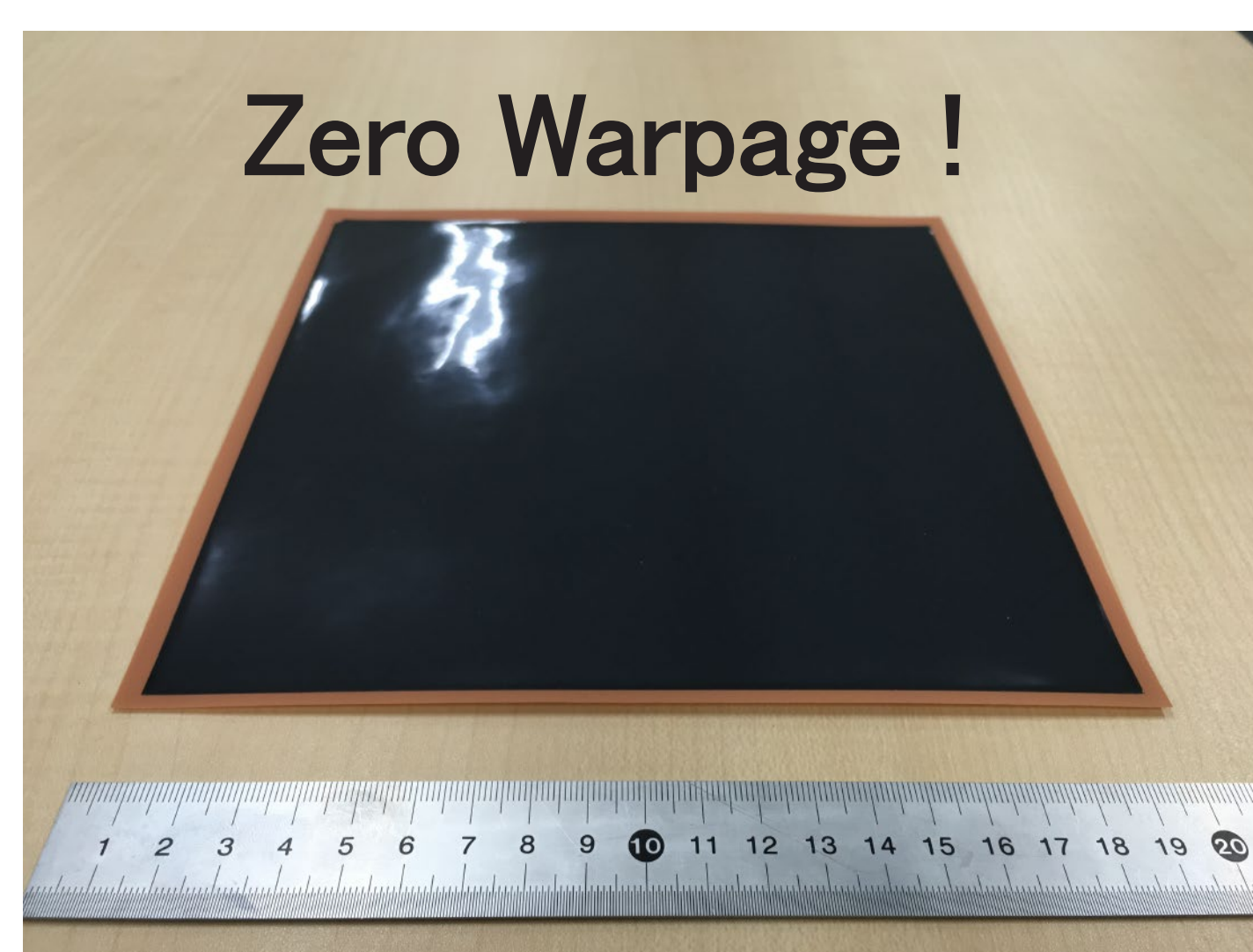


Fig. Appearance after cure of Zaristo 907

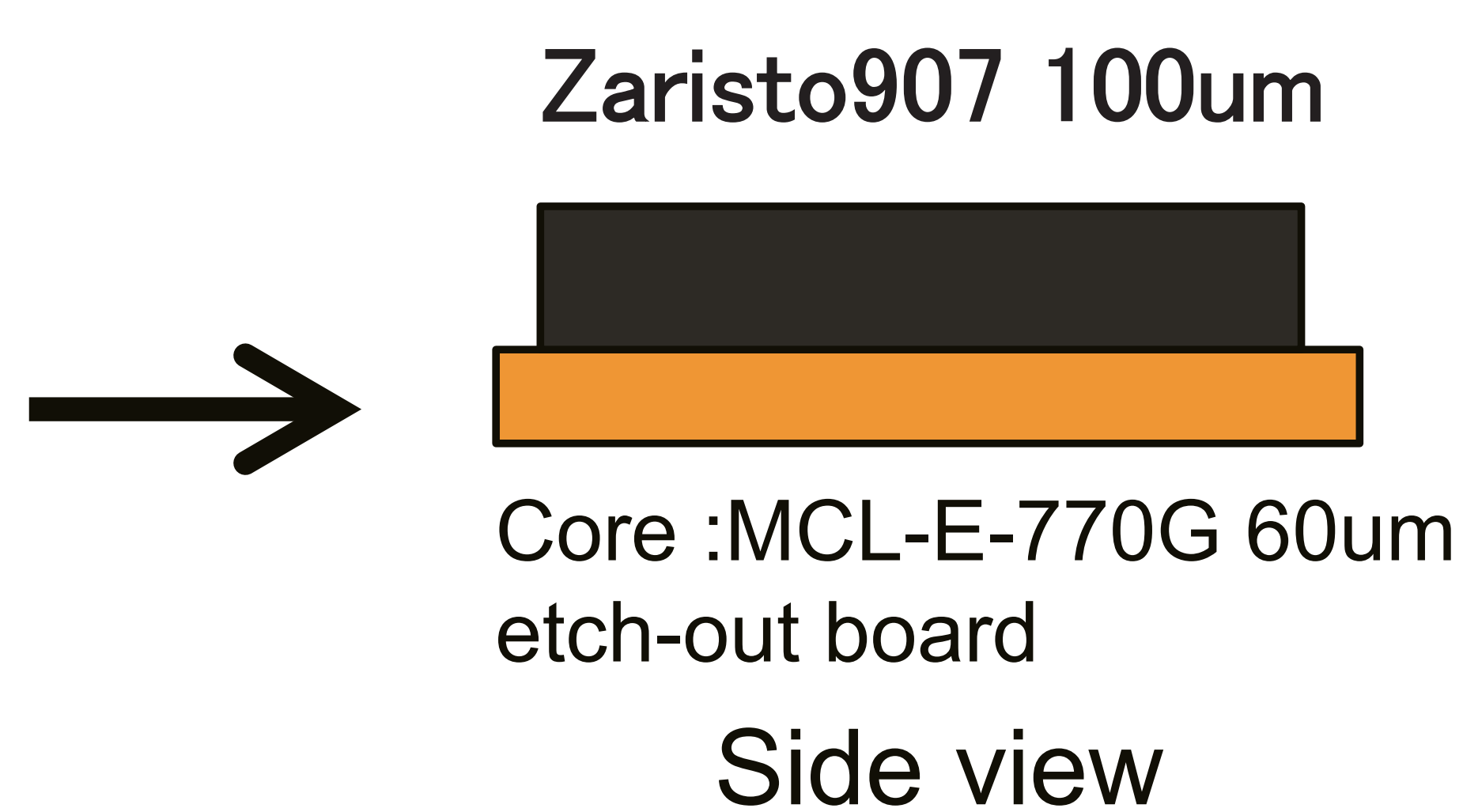


Fig. X section of ETS

特性 Properties

Test Items	Unit	Zaristo125	Zaristo517X	Zaristo907
Target Application		SAP for FC-CSP,BGA	SAP for Server	MIS, ETS
ガラス転移点 Tg(TMA)	deg.C	165-175	165-175	140-150
線膨張係数 CTE α 1	ppm	25-30	17	7-10
弾性率 Elastic Modulus	GPa	7-8	11-12	7.9-8.3
誘電率 Dk(10GHz,SPDR)		3.4	3.4	3.5-3.6
誘電正接 Df(10GHz,SPDR)		0.015	0.004-0.005	0.006-0.009
ピール強度 Peel strength Ra after Desmear	N/cm um	>5.0 0.25~0.40	4.0 0.2~0.25	Under Evaluation

Under Development